

MS2H10120G1

1200V Silicon Carbide Diode

Features

- 1200-Volt Schottky Rectifier
- Shorter recovery time
- High-speed switching possible
- High-Frequency Operation
- Temperature-Independent Switching Behavior
- Extremely Fast Switching
- Positive Temperature Coefficient on VF

Benefits

- Higher safety margin against overvoltage
- Improved efficiency all load conditions
- Increased efficiency compared to Silicon Diode alternatives
- Reduction of Heat Sink Requirements
- Parallel Devices Without Thermal Runaway
- Essentially No Switching Losses

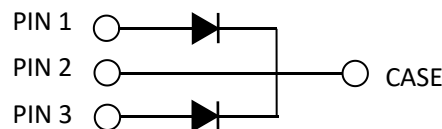
Applications

- Switch Mode Power Supplies
- Power Factor Correction
- Motor Drives
- HID Lighting

Package



Type : TO-247-3Lead



Absolute Maximum Ratings

$T_c = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	MS2H10120G1	Units
VRRM	Repetitive Peak Reverse Voltage	1200	V
VRSM	Surge Peak Reverse Voltage	1200	V
VDC	DC Blocking Voltage	1200	V
IF	Continuous Forward Current @ $T_c=150^\circ\text{C}$	10	A
	Continuous Forward Current @ $T_c=25^\circ\text{C}$	40.8	
IFRM	Repetitive Peak Forward Surge Current @ $T_c=25^\circ\text{C}$, $t_P = 10$ ms, Half Sine Wave	30	A
IFSM	Non-Repetitive Peak Forward Surge Current @ $T_c=25^\circ\text{C}$, $t_P = 10$ ms, Half Sine Wave	60	A
IF,Max	Non-Repetitive Peak Forward Surge Current ;@ $T_c=25^\circ\text{C}$, $t_P= 10$ μs , Pulse	400	A
Ptot	Power Dissipation (Per Leg/Device)	@ $T_c=25^\circ\text{C}$	130
		@ $T_c=110^\circ\text{C}$	56
TJ , Tstg	Operating Junction and Storage Temperature	-55 to +175	$^\circ\text{C}$

Electrical Characteristics

$T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Test Conditions	Test Conditions	Min	Typ	Max	Unit
VF	Forward Voltage(Per Lag)	IF=5A, TC=25° C IF=5A, TC=175° C	-	1.5 2.0	1.8 3.0	V
IR	Reverse Current	VR=1200V, TC=25° C VR=1200V, TC=175° C	-	2 50	10 100	μA
QC	Total Capacitive Charge	VR =800V, TJ = 25° C $Q_c = \int_0^{t_r} C(V) dv$	-	24	-	nC
C	Total Capacitance	VR =0V, TJ = 25° C, f=1MHz VR =400V, TJ = 25° C, f=1MHz VR =800V, TJ = 25° C, f=1MHz	-	340 22 18	-	pF
Ec	Capacitance Stored Energy	VR=800V	-	12	-	μJ

Thermal Characteristics

Symbol	Parameter	Typ	Unit
RθJC	Thermal Resistance from Junction to Case	1.15	°C/W

Typical Characteristics

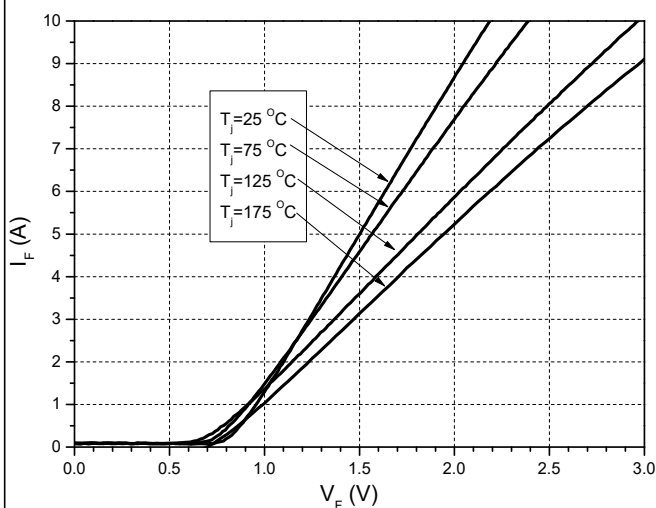


Figure 1. Forward Characteristics

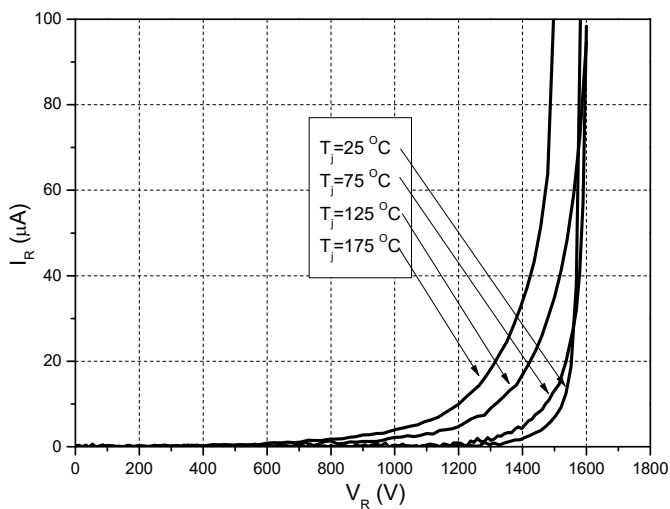


Figure 2. Reverse Characteristics

Typical Characteristics

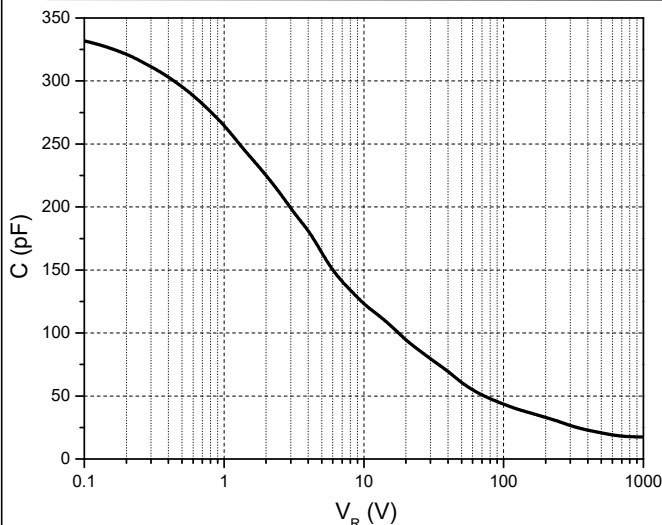


Figure 3. Capacitance vs. Reverse Voltage

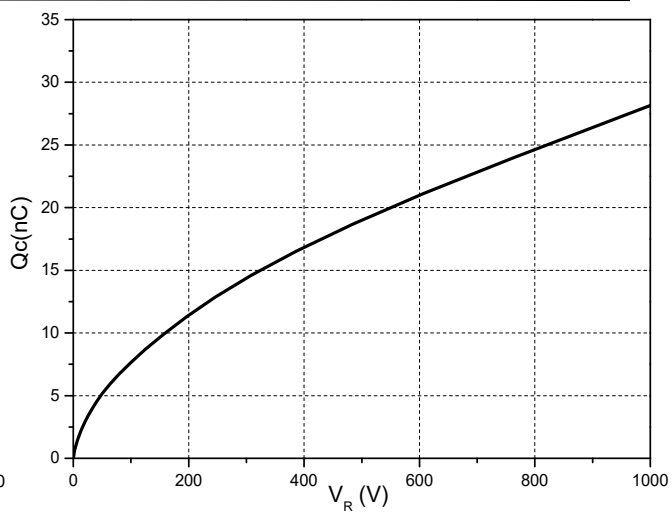


Figure 4. Total Capacitance Charge vs. Reverse Voltage

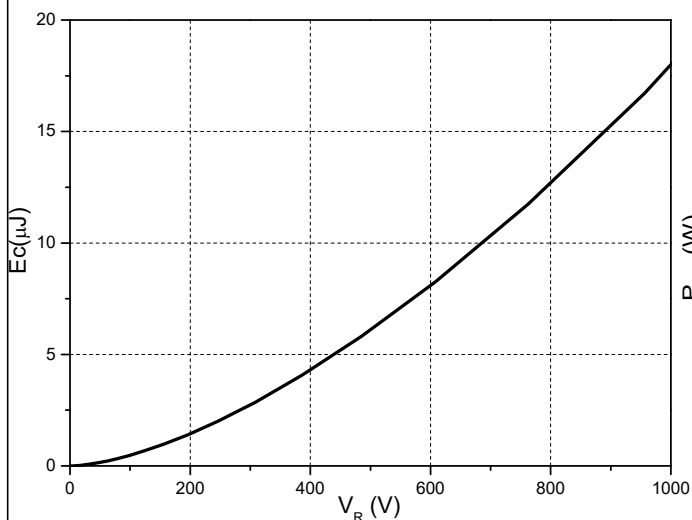


Figure 5. Capacitance Stored Energy

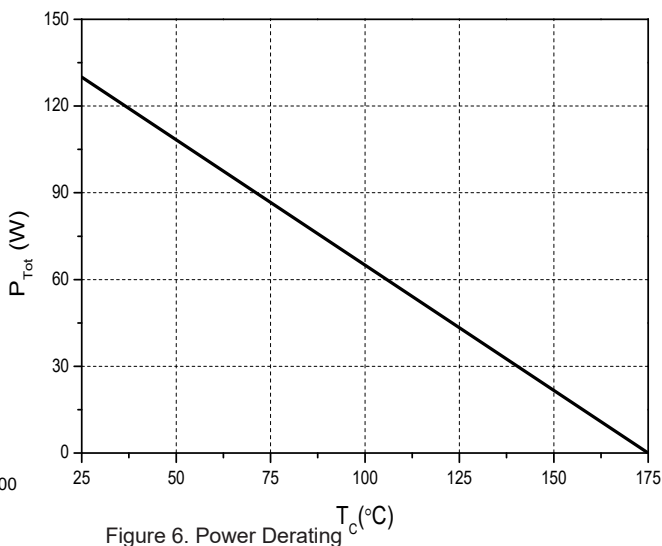


Figure 6. Power Derating $T_c (^{\circ}C)$

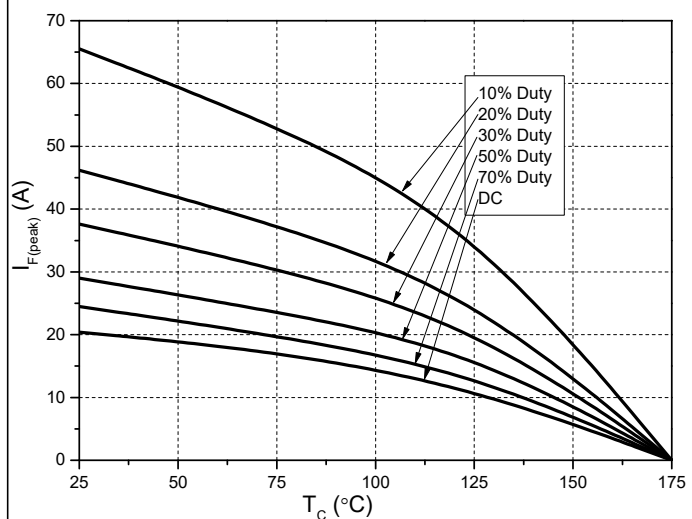


Figure 7. Current Derating

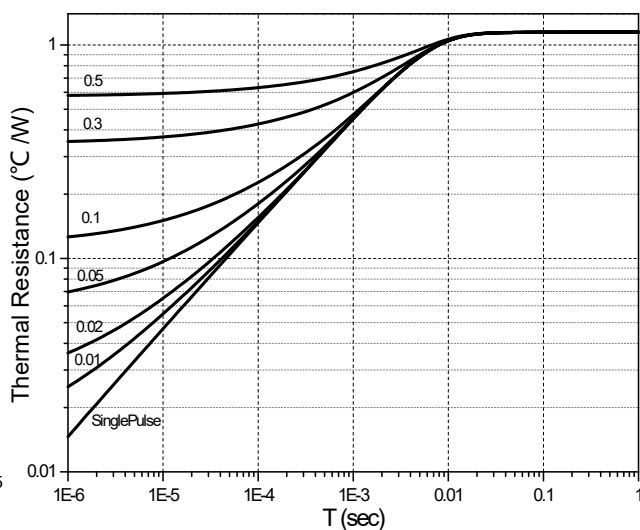
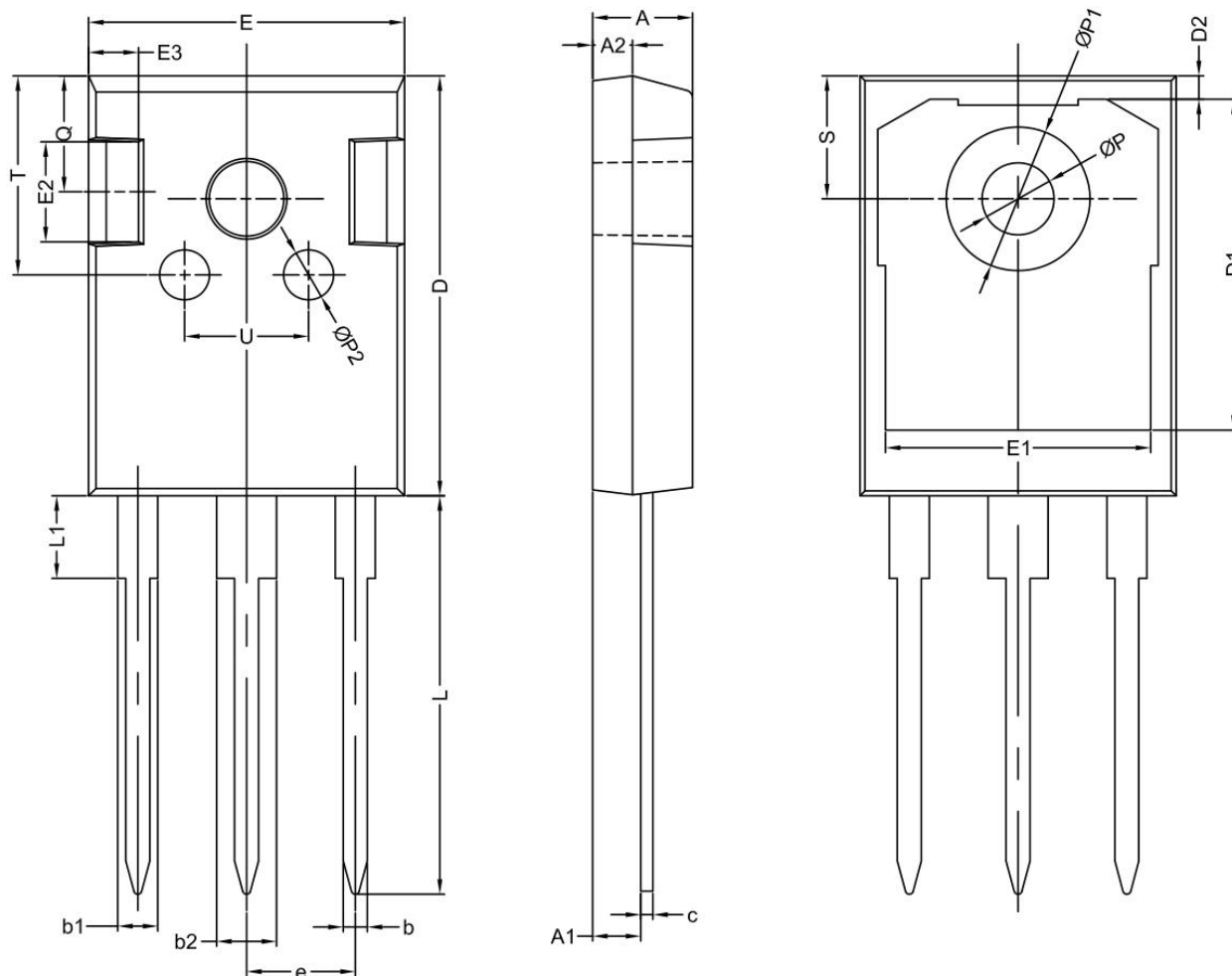


Figure 8. Transient Thermal Impedance

TO-247 OUTLINE



SYMBOL	Mechanical Dimensions/mm			SYMBOL	Mechanical Dimensions/mm			SYMBOL	Mechanical Dimensions/mm		
	MIN	NOM	MAX						MIN	NOM	MAX
A	4.80	5.00	5.20	D	20.80	21.00	21.20	L1	-	4.13	-
A1	2.21	2.41	2.61	D1	-	16.55	-	Ø P	3.5	3.6	3.7
A2	1.90	2.00	2.10	E	15.60	15.80	16.0	Ø P1	-	-	7.40
b	1.10	1.20	1.35	E1		13.3		Ø P2	-	2.50	-
b1	-	2.00	-	E2		5.0		Q	-	5.8	-
b2	-	3.00	-	e		5.44		S	6.05	6.15	6.25
c	0.55	0.60	0.75	L	19.42	19.92	20.42	T	-	10.0	-

NOTE:

- 1The plastic package is not marked as smooth surfaceRa=0.1;Subglossy surfaceRa=0.8
- 2.Undeclared tolerance ± 0.25 , Unmarked filletRmax=0.25

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